

## Design Rule Verification Report

**Date:** 04/10/2023  
**Time:** 16:14:35  
**Elapsed Time:** 00:00:07  
**Filename:** S:\School\WEMPEC\AMDC-Hardware\altium\PCB\_v6.PcbDoc

**Warnings:** 0  
**Rule Violations:** 915

## Summary

Warnings	Count
<b>Total</b>	<b>0</b>

Rule Violations	Count
<a href="#">Clearance Constraint (Gap=6mil)_(All),(All)</a>	0
<a href="#">Clearance Constraint (Gap=10mil)_(InPolygon),(All)</a>	0
<a href="#">Short-Circuit Constraint (Allowed=No)_(All),(All)</a>	0
<a href="#">Un-Routed Net Constraint (.All)</a>	0
<a href="#">Modified Polygon (Allow modified: No),(Allow shelved: No)</a>	0
<a href="#">Width Constraint (Min=20mil)_(Max=40mil)_(Preferred=30mil)_(InNetClass('Power'))</a>	0
<a href="#">Width Constraint (Min=10mil)_(Max=40mil)_(Preferred=20mil)_(InNetClass('3V3'))</a>	0
<a href="#">Width Constraint (Min=10mil)_(Max=40mil)_(Preferred=20mil)_(InNet('GND'))</a>	0
<a href="#">Width Constraint (Min=6mil)_(Max=100mil)_(Preferred=10mil)_(All)</a>	0
<a href="#">Power Plane Connect Rule(Relief Connect)_(Expansion=4mil)_(Conductor Width=6mil)_(Air Gap=6mil)_(Entries=4)_(All)</a>	0
<a href="#">Minimum Annular Ring (Minimum=6mil)_(All)</a>	0
<a href="#">Hole Size Constraint (Min=11.811mil)_(Max=255.905mil)_(All)</a>	0
<a href="#">Hole To Hole Clearance (Gap=10mil)_(All),(All)</a>	0
<a href="#">Minimum Solder Mask Sliver (Gap=6mil)_(All),(All)</a>	416
<a href="#">Silk To Solder Mask (Clearance=5mil)_(IsPad),(All)</a>	499
<a href="#">Silk to Silk (Clearance=0mil)_(All),(All)</a>	0
<a href="#">Net Antennae (Tolerance=0mil)_(All)</a>	0
<a href="#">Board Clearance Constraint (Gap=0mil)_(All - (OnTopSilkscreen Or OnBottomSilkscreen))</a>	0
<a href="#">Matched Lengths(Tolerance=50mil)_(InNetClass('Ethernet'))</a>	0
<a href="#">Height Constraint (Min=0mil)_(Max=5000mil)_(Preferred=500mil)_(All)</a>	0
<b>Total</b>	<b>915</b>

### Minimum Solder Mask Sliver (Gap=6mil) (All),(All)

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-1(4940.551mil,4437.283mil) on Bottom Layer And Pad U1-2(4960.236mil,4437.283mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-10(5117.717mil,4437.283mil) on Bottom Layer And Pad U1-11(5137.402mil,4437.283mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-10(5117.717mil,4437.283mil) on Bottom Layer And Pad U1-9(5098.032mil,4437.283mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-11(5137.402mil,4437.283mil) on Bottom Layer And Pad U1-12(5157.087mil,4437.283mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-12(5157.087mil,4437.283mil) on Bottom Layer And Pad U1-13(5176.772mil,4437.283mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-13(5176.772mil,4437.283mil) on Bottom Layer And Pad U1-14(5196.457mil,4437.283mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-15(5225mil,4408.74mil) on Bottom Layer And Pad U1-16(5225mil,4389.055mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-16(5225mil,4389.055mil) on Bottom Layer And Pad U1-17(5225mil,4369.37mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-17(5225mil,4369.37mil) on Bottom Layer And Pad U1-18(5225mil,4349.685mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-18(5225mil,4349.685mil) on Bottom Layer And Pad U1-19(5225mil,4330mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-19(5225mil,4330mil) on Bottom Layer And Pad U1-20(5225mil,4310.315mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-2(4960.236mil,4437.283mil) on Bottom Layer And Pad U1-3(4979.921mil,4437.283mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-20(5225mil,4310.315mil) on Bottom Layer And Pad U1-21(5225mil,4290.63mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U12-1(3128.163mil,3401.004mil) on Bottom Layer And Pad U12-2(3128.163mil,3375.414mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-21(5225mil,4290.63mil) on Bottom Layer And Pad U1-22(5225mil,4270.945mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U12-2(3128.163mil,3375.414mil) on Bottom Layer And Pad U12-3(3128.163mil,3349.823mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-22(5225mil,4270.945mil) on Bottom Layer And Pad U1-23(5225mil,4251.26mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-23(5225mil,4251.26mil) on Bottom Layer And Pad U1-24(5225mil,4231.575mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U12-4(3043.517mil,3349.823mil) on Bottom Layer And Pad U12-5(3043.517mil,3375.414mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-24(5225mil,4231.575mil) on Bottom Layer And Pad U1-25(5225mil,4211.89mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U12-5(3043.517mil,3375.414mil) on Bottom Layer And Pad U12-6(3043.517mil,3401.004mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-25(5225mil,4211.89mil) on Bottom Layer And Pad U1-26(5225mil,4192.205mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-27(5196.457mil,4163.662mil) on Bottom Layer And Pad U1-28(5176.772mil,4163.662mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-28(5176.772mil,4163.662mil) on Bottom Layer And Pad U1-29(5157.087mil,4163.662mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]

Minimum Solder Mask Sliver Constraint: (5.906mil < 6mil) Between Pad U1-29(5157.087mil,4163.662mil) on Bottom Layer And Pad U1-30(5137.402mil,4163.662mil) on Bottom Layer [Bottom Solder] Mask Sliver [5.906mil]







[Silk To Solder Mask Clearance Constraint: \(3.933mil < 5mil\) Between Pad U6-7\(6623.953mil,2195.291mil\) on Top Layer And Track \(6459.583mil,2234.662mil\)\(6660.37mil,2234.662mil\) on Top Overlay \[Top Overlay\] to \[Top Solder\] clearance \[3.933mil\]](#)

[Silk To Solder Mask Clearance Constraint: \(3.933mil < 5mil\) Between Pad U6-8\(6649.543mil,2195.291mil\) on Top Layer And Track \(6459.583mil,2234.662mil\)\(6660.37mil,2234.662mil\) on Top Overlay \[Top Overlay\] to \[Top Solder\] clearance \[3.933mil\]](#)

[Silk To Solder Mask Clearance Constraint: \(3.933mil < 5mil\) Between Pad U6-9\(6649.543mil,2407.89mil\) on Top Layer And Track \(6459.583mil,2368.52mil\)\(6660.37mil,2368.52mil\) on Top Overlay \[Top Overlay\] to \[Top Solder\] clearance \[3.933mil\]](#)

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